

XFP

Amphenol ICC's XFP connector system is a 30 position 0.8 mm pitch SMT receptacle designed to support 10 Gigabit Fibre Channel and Gigabit Ethernet with the ability to extend performance to 14Gb/s. It is constructed from a metal frame and the cage assembly is to be bezel-mounted to an I/O panel with compliant pins for pressing onto the host PCB. Its single row cage configuration requires less space and is a cost optimized alternative to parallel-optics VSR. XFP also requires less than one-third the power and physical space of an MSA interconnect with parallel interface. It has a single footprint for all links and is hot-pluggable. The cage assembly has several EMI shielding options such as an elastomeric gasket, which blocks EMI emissions coming from the transceiver when installed.



TARGET MARKETS



TECHNICAL INFORMATION

MATERIAL

- Housing: Black color, Glass reinforced, Lead Free Solder Reflow Process Compatible Thermo Plastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin or gold flash options
- Plating Mating Area: Gold

MECHANICAL PERFORMANCE

- Durability: 250 mating cycles
- Mating Force: 40 N max.
- Contact Normal Force: 100 grams
- PCB Thickness Single Side Mounting (Cage): 1.57 mm (0.062 in.)
- PCB Thickness Double Side Mounting (Cage): 3.00 mm (0.118 in.)
- Unmating Force (Cage): 30 N max.
- Insertion Force to PCB (Cage): 133N min.

ELECTRICAL PERFORMANCE

- Operating Voltage: 30 VDC per contact
- Operating Current: 0.5 A percontact
- Differential Impedance: 100Ω +/- 10Ω

ENVIRONMENTAL

- Operating and (Storage) Temperature: -40° to +85° C
- RoHS & Halogen-Free

TOOLING INFORMATION

- Configurations: 1x1

TARGET MARKETS/APPLICATIONS

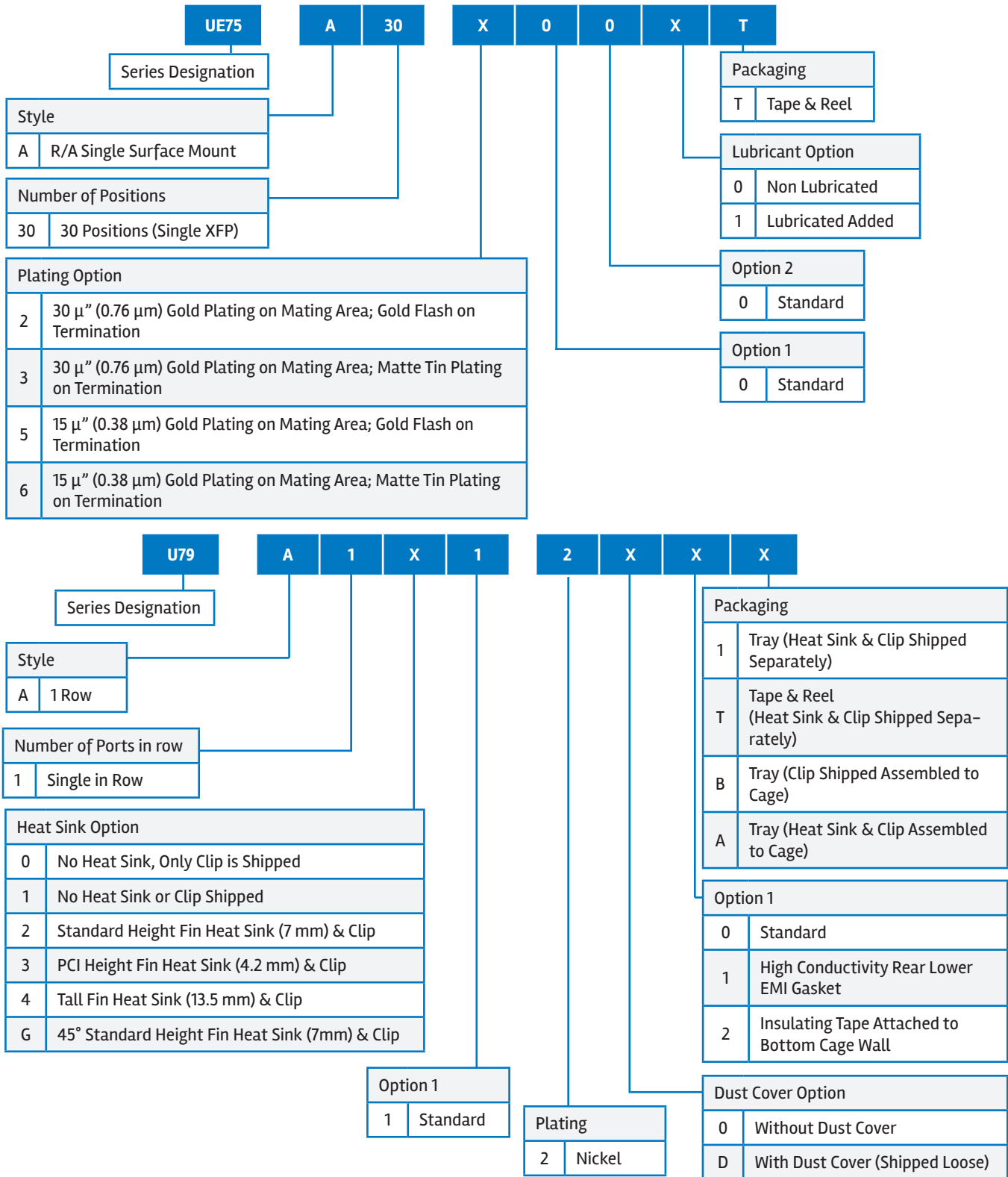


Data Networking Equipment
Telecommunication Network



Storage

PART NUMBER SELECTOR



HS100XFP118EA4